



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

*: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-05-08
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS/IPD Materials Declaration Champion)
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	A627*UR15AJ6	A	MU1A	2014-05-08
Amount	UoM	Unit type	ST ECOPACK Grade	
534.52	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	250	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	12.8X7.5X2.5	26	gull wing	
Comment	Package: SO 20 .30 TO JEDEC MS-013; MD valid also for L6205D013TR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	A6Z7*UR15AJ6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	14.632	mg	supplier	die	Silicon (Si)	7440-21-3		14.193	mg	969997	26553
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.107	mg	7313	200
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.012	mg	820	22
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.032	mg	2187	60
die (s)				supplier	passivation	Silicon Oxide (SiO2)	7631-86-9		0.185	mg	12644	346
die (s)				supplier	passivation	Gamma-butyrolactone	96-48-0		0.062	mg	4237	116
die (s)				supplier	passivation	Polyhydroxyamide	55295-98-2		0.028	mg	1914	52
die (s)				supplier	passivation	Alcoxysilane	proprietary		0.002	mg	137	4
die (s)				supplier	passivation	Aryl Siliclic Acid	proprietary		0.001	mg	68	2
die (s)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.001	mg	68	2
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	137	4
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.007	mg	478	13
Leadframe	Copper & Its alloys	177.165	mg	supplier	alloy	Copper (Cu)	7440-50-8		176.857	mg	998262	330871
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.081	mg	457	152
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.149	mg	841	279
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.071	mg	401	133
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.005	mg	28	9
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.002	mg	11	4
Die attach	Other Organic Materials	2.455	mg	supplier	glue	Silver (Ag)	7440-22-4		1.842	mg	750305	3446
Die attach				supplier	glue	Epoxy Cresol Novolak	29690-82-2		0.606	mg	246843	1134
Die attach				supplier	glue	tert-butanol	75-65-0		0.002	mg	815	4
Die attach				supplier	glue	1-Isopropyl-2,2-dimethyltrimethylene diisobut	6846-50-0		0.005	mg	2037	9
Bonding wire	Other inorganic materials	0.845	mg	supplier	wire	Gold (Au)	7440-57-5		0.845	mg	1000000	1581
encapsulation	Other Organic Materials	339.423	mg	supplier	mold compound	Silica, vitreous	60676-86-0		271.539	mg	800002	508005
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		23.76	mg	70001	44451
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		13.577	mg	40000	25400
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		20.365	mg	59999	38100
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		4.073	mg	12000	7620
encapsulation				JIG 1	mold compound	Brominated Epoxy Resin	40039-93-8		5.091	mg	14999	9524
encapsulation				supplier	mold compound	Carbon black	1333-86-4		1.018	mg	2999	1905